

ABSTRACT

Methods and apparatus that minimize the impedance discontinuity between a component and a signal trace is described. The methods and apparatus generally 5 comprise at least one signal trace disposed on a dielectric layer, wherein the signal trace comprises a first width which is wider than a second width, a via connected to the first width of the signal trace, and a component electrically attached to the via, wherein an impedance discontinuity between the signal trace and the component is lowered.

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